ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® INDUSTRIES® INTERNATION CONNECTING	ockburn, Illinois. A	Il rights reserved un ntions.	nder both Ie	his docume vel parts, t	ent is a declarati he declaration e	on of the substancompasses all	nces within the manufactu lower level materials for v	arer listed ite which the ma	em. Note: if anufacturer l	the item is an as has engineering	sembly with lower responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information							
Supplier Information												
ompany name* Company unique ID				Unique ID Authority			Response Date*					
onsemi	emi								2023-06-06			
Contact Name	Title - Contact]	Phone - Contact*				Email - Contact*			
Product-Env-Stewards	t-Env-Stewards Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
uthorized Representative* Title - Representative				Phone - Representative*				Email - Representative*				
Product-Env-Stewards Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Requester Item Number Mfr	Item Number	Mfr Item Name			Effective Date	Version	Manufacturing Site	V	Veight*	UOM	Unit Type	
ULI	2003ADR2G DARLINGTON TR		RANS ARRAY		2023-06-06		PH1		42.68	mg	Each	
Manufacturing Proccess Information					•	·	·					
Terminal Plating / Grid Array Material	Array Material Terminal Base Alloy J		-STD-020 MSL R	Rating	Peak Process Body Temperatur		erature Max Time at Peak	k Temperatu	ire Numbe	er of Reflow Cyc	les	
Matte Tin (Sn) - annealed CU Alloy 1					260	С	30	second	ls 3			
Comments												
level 1 - maximum time at peak temperature durin	g soldering is 10-3	0 seconds										
For more information regarding material composi	tion please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		nium (Cr6+), Polybro	ominated Biphenyls (PBB), Polybron	dmium and quantity limit of 0.1% by mass (100 minated Diphenyl Ethers (PBDE), and Bis(2-eth						
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the					
Supplier Digital Signature Ra	stislav Drska	Le								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	2.73	mg	Supplier	Silicon (Si)	7440-21-3		2.73	mg
Die Attach	4.85	mg		Epoxy resin	proprietary data		0.1212	mg
			Supplier	Silver (Ag)	7440-22-4		4.0982	mg
			Supplier	Phenolic Resin	Proprietary Data		0.1212	mg
			Supplier	Inorganic filler	Proprietary Data		0.1212	mg
			Supplier	Dicyandiamine	461-58-5		0.0242	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.3637	mg
Lead Frame	75.92	mg	Supplier	Silver (Ag)	7440-22-4		0.7592	mg
			Supplier	Zinc (Zn)	7440-66-6		0.1518	mg
			Supplier	Iron (Fe)	7439-89-6		1.9739	mg
			Supplier	Copper (Cu)	7440-50-8		73.035	mg
Mold Compound-Black	55.11	mg		Epoxy resin	proprietary data		2.7555	mg
			Supplier	Phenolic Resin	Proprietary Data		1.1022	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		1.3778	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2756	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		49.599	mg
lating	3.73	mg	Supplier	Tin (Sn)	7440-31-5		3.73	mg
Wire Bond - Cu	0.34	mg	Supplier	Copper (Cu)	7440-50-8		0.34	mg